

Claim Amendments

1. (currently amended) A non-volatile memory package comprising:
a substrate having a first surface and a second surface;
an integrated circuit die including a memory array mounted to the first surface of the substrate; and
a passive component mounted to the second surface of the substrate;
wherein the passive component is at least a portion of a voltage regulator circuit coupled to the integrated circuit die.
2. (original) The non-volatile memory package of claim 1, wherein the passive component is electrically coupled to the integrated circuit die.
3. (original) The non-volatile memory package of claim 1, further comprising an array of solder balls mounted to the substrate.
4. (original) The non-volatile memory package of claim 3, wherein the passive component is located centrally within the array of solder balls.
5. (original) The non-volatile memory package of claim 4, wherein the passive component has a height less than a height of the solder balls.
6. (canceled)
7. (original) The non-volatile memory package of claim 1, wherein the substrate

comprises a cavity and at least a portion of the passive component lies within the cavity.

8. (original) The non-volatile memory package of claim 7, further comprising an array of solder balls mounted to the substrate, wherein the passive component has a height less than a height of the solder balls.

10. (original) The non-volatile memory package of claim 1, wherein the passive component is mounted to the substrate with an epoxy material.

11. (original) The non-volatile memory package of claim 10, wherein the epoxy material between the passive component and the substrate is less than about 0.1 millimeters in thickness.

12. (original) The non-volatile memory package of claim 1, wherein the passive component is mounted to the substrate with a conductive material.

13. (original) The non-volatile memory package of claim 1, wherein the passive component includes a capacitor or an inductor.

14. (original) The non-volatile memory package of claim 1, wherein the integrated circuit die includes a flash memory array.

Second occurrence of Claims 13-14 (Canceled)

Claims 15-20 (Canceled)